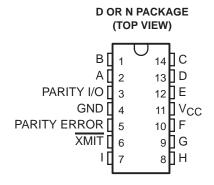
SCAS069B - AUGUST 1988 - REVISED APRIL 1996

- Inputs Are TTL-Voltage Compatible
- Generates Either Odd or Even Parity for Nine Data Lines
- Cascadable for n-Bits Parity
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic 300-mil DIPs (N)



description

The 74ACT11286 universal 9-bit parity generator/checker features a local output for parity checking and a bus-driving parity I/O port for parity generation/checking. The word-length capability is easily expanded by cascading.

The XMIT control input is implemented specifically to accommodate cascading. When the XMIT is low, the parity tree is disabled and the PARITY ERROR output remains at a high logic level, regardless of the input levels. When XMIT is high, the parity tree is enabled. PARITY ERROR indicates a parity error when either an even number of inputs (A through I) are high and PARITY I/O is forced to a low logic level, or when an odd number of inputs are high and PARITY I/O is forced to a high logic level.

The I/O control circuitry is designed so that the I/O port remains in the high-impedance state during power up or power down, to prevent bus glitches.

The 74ACT11286 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

NUMBER OF INPUTS (A-I) THAT ARE HIGH	TS XMIT PARITY I/O		PARITY ERROR OUTPUT
0, 2, 4, 6, 8	I	Н	Н
1, 3, 5, 7, 9	I	L	Н
0.0.4.0.0	h	h	Н
0, 2, 4, 6, 8	h	1	L
40570	h	h	L
1, 3, 5, 7, 9	h	1	Н

 $h=\mbox{high input level},\, H=\mbox{high output level},\, I=\mbox{low input level},\, L=\mbox{low output level}$

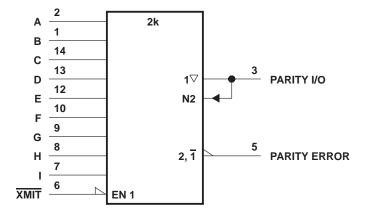


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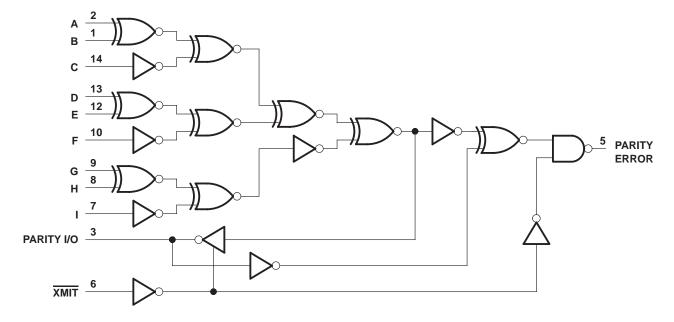


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





74ACT11286 9-BIT PARITY GENERATOR/CHECKER WITH BUS DRIVER PARITY I/O PORTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	_0.5 \/ to 7 \/
Input voltage range, V _I (see Note 1)	-0.5 V to V_{CC} + 0.5 V
Output voltage range, V _O (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): D package	1.25 W
N package	1.1 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero.

recommended operating conditions

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		8.0	V
VI	Input voltage	0	VCC	V
VO	Output voltage	0	VCC	V
IOH	High-level output current		-24	mA
l _{OL}	Low-level output current		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
TA	Operating free-air temperature	-40	85	°C

74ACT11286 9-BIT PARITY GENERATOR/CHECKER WITH BUS DRIVER PARITY I/O PORTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS		T,	Վ = 25° C	;	BAIN	MAY		
PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	MIN	MAX	UNIT	
		J	4.5 V	4.4			4.4			
		I _{OH} = -50 μA		5.4			5.4			
Voн		1 24 m A	4.5 V	3.94			3.8		V	
		I _{OH} = -24 mA	5.5 V	4.94			4.8			
		I _{OH} = -75 mA [†]					3.85		1	
		L 50 A	4.5 V			0.1		0.1		
		I _L = 50 μA				0.1		0.1		
VOL			4.5 V			0.36		0.44	V	
		I _{OL} = 24 mA				0.36		0.44		
		I _{OL} = 75 mA [†]						1.65		
loz	PARITY I/O	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±5	μΑ	
lį	Except PARITY I/O	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1	μΑ	
lcc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μΑ	
ΔI _{CC} ‡		One input at 3.4 V, Other inputs at GND or V _{CC}				0.9		1	mA	
Ci		V _I = V _{CC} or GND	5 V		3.5				pF	
Co	PARITY I/O	$V_O = V_{CC}$ or GND	5 V		8				pF	

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recomended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

	FROM TO							
PARAMETER	(INPUT)	TO (OUTPUT)	MIN	T _A = 25°C MIN TYP MAX		MIN	MAX	UNIT
t _{PLH}		545/FV/V0	2.7	6.1	9	2.7	10.4	
^t PHL	Any A–I	PARITY I/O	3.6	7.3	10.8	3.6	12	ns
^t PLH		DADITY EDDOD	3	6.9	9.7	3	11.3	
^t PHL	Any A–I	PARITY ERROR	3.9	7.7	11.4	3.9	12.9	ns
^t PLH	DADITY/I/O	DADITY EDDOD	2.2	4.6	6.8	2.2	7.7	
^t PHL	PARITY I/O	PARITY ERROR	3.1	5.6	8.3	3.1	9.1	ns
^t PZH	V4.41=	DA DITY I/O	1.8	4.2	6.3	1.8	7.3	
t _{PZL}	XMIT	PARITY I/O	3	6.3	9.4	3	11.4	ns
^t PHZ	XMIT	DARITY I/O	4.7	6.5	7.9	4.7	8.5	20
^t PLZ	AIVII I	PARITY I/O	4.1	6	7.3	4.1	7.8	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

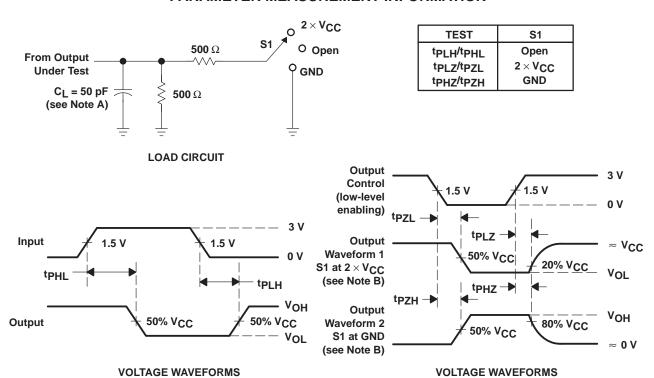
	PARAMETER	TEST CON	TYP	UNIT		
		Outputs enabled	0 50 5		56	1
C _{pd}	Power dissipation capacitance	Outputs disabled	$C_L = 50 \text{ pF},$	f = 1 MHz	50	pF



[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V to V_{CC}.

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
74ACT11286D	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT11286
74ACT11286D.A	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT11286

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74ACT11286D	D	SOIC	14	50	506.6	8	3940	4.32
74ACT11286D.A	D	SOIC	14	50	506.6	8	3940	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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